Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3 X 3 X 0.75 (1.64 X 2.38 EP)
Lead Count	10
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.21E-02	86.2	862000	35.03	350284
Thermosets	Epoxy resin	Proprietary	8.40E-04	6.0	60000	2.44	24382
Thermosets	Phenol resin	Proprietary	8.40E-04	6.0	60000	2.44	24382
Other inorganic materials	Metal Hydroxide	Proprietary	2.10E-04	1.5	15000	0.61	6095
Other inorganic materials	Carbon black	1333-86-4	4.20E-05	0.3	3000	0.12	1219
Subtotal			1.40 E-02	100.00	1000000	40.64	406362

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.67 E-02	99.25	992500	48.40	483978
Copper & its alloys	Chromium	7440-47-3	5.04 E-05	0.30	3000	0.15	1463
Copper & its alloys	Tin	7440-31-5	4.20 E-05	0.25	2500	0.12	1219
Copper & its alloys	Zinc	7440-66-6	3.36 E-05	0.20	2000	0.10	975
Subtotal			1.68 E-02	100.00	1000000	48.76	487635

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.20 E-05	100.0	1000000	0.12	1219

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	8.00 E-04	100.0	1000000	2.32	23221

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.00 E-05	100.0	1000000	0.03	290

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.60 E-03	100.0	1000000	7.55	75467

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.47 E-04	73.40	734000	0.43	4261
Thermoset	Epoxy Resin	Proprietary	3.67 E-05	18.35	183500	0.11	1065
Other organic materials	Metal oxide	Proprietary	5.50 E-06	2.75	27500	0.02	160
Other organic materials	Amine	Proprietary	5.50 E-06	2.75	27500	0.02	160
Other organic materials	Gamma Butyrolactone	Proprietary	5.50 E-06	2.75	27500	0.02	160
Subtotal			2.00 E-04	100.0	1000000	0.58	5805

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.45 E-02**	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES